



PK495 (v1.0) November 18, 2011

# 100% Material Declaration Data Sheet for Spartan®-3/-3E/-3A VQ100 Package (Cu Wire)

**Average Weight: 0.548 g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					<b>0.010916</b>	<b>1.991</b>
	Silicon (Si)	7440-21-3	100.00		0.010916	
Die Attach					<b>0.002731</b>	<b>0.498</b>
	Silver (Ag)	7440-22-4	73.00		0.001994	
	Epoxy (EP)	Trade Secret	13.50		0.000369	
	Anhydride	Trade Secret	10.50		0.000287	
	1,4-Butanedioldiglycidyl	Trade Secret	3.00		0.000082	
Mold Compound					<b>0.380843</b>	<b>69.465</b>
	Epoxy Resin	Trade secret	7.00		0.026659	
	Phenol Resin	Trade secret	5.00		0.019042	
	Carbon Black	1333-86-4	0.30		0.001143	
	Fused Silica	60676-86-0	77.40		0.294772	
	Silica Fused	7631-86-9	10.00		0.038084	
	Silica, crystalline	14808-60-7	0.30		0.001143	
Leadframe					<b>0.145613</b>	<b>26.559</b>
	Copper (Cu)	7440-50-8	94.30		0.137313	
	Nickel (Ni)	7440-02-0	3.20		0.004660	
	Silver (Ag)	7440-22-4	1.60		0.002330	
	Silicon (Si)	7440-21-3	0.73		0.001056	
	Magnesium (Mg)	7439-95-4	0.18		0.000255	
Solder Plating					<b>0.007300</b>	<b>1.332</b>
	Tin (Sn)	7440-31-5	85.00		0.006205	
	Lead (Pb)	7439-92-1	15.00		0.001095	
Copper Wire					<b>0.000851</b>	<b>0.155</b>
	Copper (Cu)	7440-50-8	97.28		0.000828	
	Palladium	7440-05-3	2.70		0.000023	
	Impurities	N/A	0.02		0.000000	

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
11/18/11	1.0	Initial Xilinx release.

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